



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**Notification# 20221018003.0**  
**Datasheet for CDx4HC73, CD74HCT73, CDx4HC112, CDx4HCT112, CDx4HC688,**  
**CDx4HCT688**  
**Information Only**

**Date:** October 19, 2022  
**To:** TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)).

Sincerely,

PCN Team  
SC Business Services




**Information Only  
Attachments**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
CD74HC688NSR	null
CD74HC112NSR	null
CD74HC112E	null
CD74HC688E	null
CD74HC73M96	null

Technical details of this Product Change follow on the next page(s).

<b>Notification Number:</b>	20221018003.0	<b>Notification Date:</b>	October 19, 2022
<b>Title:</b>	Datasheet for CDx4HC73, CD74HCT73, CDx4HC112, CDx4HCT112, CDx4HC688, CDx4HCT688		
<b>Customer Contact:</b>	PCN Manager	<b>Dept:</b>	Quality Services
<b>Change Type:</b>			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials	
		<input type="checkbox"/> Wafer Fab Process	
<b>Notification Details</b>			
<b>Description of Change:</b>			
<p>Texas Instruments Incorporated is announcing an information only notification.  The product datasheet(s) is being updated as summarized below.  The following change history provides further details.</p>			
 <div style="float: right; text-align: right;"> <b>CD54HC73, CD74HC73, CD74HCT73</b>  <small>SCHS134G – FEBRUARY 1998 – REVISED OCTOBER 2022</small> </div>			
<b>Changes from Revision F (January 2022) to Revision G (October 2022)</b>			<b>Page</b>
<ul style="list-style-type: none"> <li>Increased RθJA for packages: D (86 to 138.7); N (80 to 91).....</li> </ul>			4
 <div style="float: right; text-align: right;"> <b>CD54HC112, CD74HC112, CD54HCT112, CD74HCT112</b>  <small>SCHS141J – MARCH 1998 – REVISED OCTOBER 2022</small> </div>			
<b>Changes from Revision I (January 2022) to Revision J (October 2022)</b>			<b>Page</b>
<ul style="list-style-type: none"> <li>Increased RθJA for packages: D (73 to 117.2); N (67 to 69.3); NS (64 to 88.4); PW (108 to 137.5).....</li> </ul>			4
 <div style="float: right; text-align: right;"> <b>CD54HC688, CD74HC688, CD54HCT688, CD74HCT688</b>  <small>SCHS196E – SEPTEMBER 1997 – REVISED OCTOBER 2022</small> </div>			
<b>Changes from Revision D (February 2022) to Revision E (October 2022)</b>			<b>Page</b>
<ul style="list-style-type: none"> <li>Increased RθJA for packages: DW (58 to 109.1); N (69 to 84.6); NS (60 to 113.4); PW (83 to 131.8).....</li> </ul>			4
The datasheet number will be changing.			
Device Family	Change From:	Change To:	
CDx4HC73, CD74HCT73	SCHS134F	SCHS134G	
CDx4HC112, CDx4HCT112	SCHS141I	SCHS141J	
CDx4HC688, CDx4HCT688	SCHS196D	SCHS196E	
<p>These changes may be reviewed at the datasheet links provided.</p> <p><a href="https://www.ti.com/product/CD54HC73">https://www.ti.com/product/CD54HC73</a></p> <p><a href="https://www.ti.com/product/CD54HC112">https://www.ti.com/product/CD54HC112</a></p> <p><a href="https://www.ti.com/product/CD54HC688">https://www.ti.com/product/CD54HC688</a></p> <p><b>Error! Bookmark not defined.</b></p>			
<b>Reason for Change:</b>			
To accurately reflect device characteristics.			

<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
<b>Changes to product identification resulting from this notification:</b>			
None.			
<b>Product Affected:</b>			
CD74HC112E	CD74HC112PWT	CD74HC73E	CD74HCT688EE4
CD74HC112M96	CD74HC688E	CD74HC73M	CD74HCT688M
CD74HC112MT	CD74HC688M	CD74HC73M96	CD74HCT688M96
CD74HC112NSR	CD74HC688M96	CD74HC73MT	CD74HCT73E
CD74HC112PW	CD74HC688NSR	CD74HCT112E	CD74HCT73M
CD74HC112PWR	CD74HC688PWR	CD74HCT688E	CD74HCT73M96
CD74HC112PWRE4	CD74HC688PWT		

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale ([www.ti.com/legal/termsofsale.html](http://www.ti.com/legal/termsofsale.html)) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.